

Peelable Solder Mask

This PCB solder mask is a synthetic latex product for the temporary masking of circuit areas and contacts against solder, rosin and cleaning fluids. It provides effective protection for contacts, gold fingers and printed circuit card edges, and can easily be peeled off once the wave soldering process is complete, and after any subsequently applied conformal coating is sufficiently dry.

Our peelable solder mask can be applied by hand or by template screening, but not by silk screening. It can also be applied using robotic or pneumatic systems.



Features & Benefits

- Withstands wave soldering
- Non-Corrosive—Safe for copper, gold, silver, and solder joints
- Solvent Solubility—Largely insoluble once cured (flux and cleaning solvent resistant)
- Water Soluble—Can be thinned with deionized (D.I.) water to adjust viscosity
- Immersion Resistant—insoluble once cured
- Room Temperature Cures or Quick Heat Curing
- Cure Monitoring Color Change—Changes from opaque pink to translucent red once cured
- Ammonia-free—does not discolor copper traces

Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
862-250ML	Tube	250 mL	250 g

Contact Information

MG Chemicals, 1210 Corporate Drive
Burlington, Ontario, Canada L7L 5R6

Email: support@mgchemicals.com

Phone: North America: +(1)800-340-0772
International: +(1) 905-331-1396
Europe: +(44)1663 362888

Cured Properties

Aqueous Solubility	Insoluble
Solvent Solubility	Low or insoluble
Weight Loss @ 200 °C, 10 °C/min	2.0 %
@ 225 °C, 10 °C/min	4.3 %
@ 250 °C, 10 °C/min	7.7 %
Wave Solder Tolerant	Yes
Peelability	Excellent
Service Temperature Range	-50–150 °C

Usage Parameters

Cure Time	60 min @ 22 °C
	30 min @ 65 °C
	20 min @ 80 °C
Max. Intermittent Temperature	250 °C
Recommended Thickness	500–760 µm
Theoretical Coverage @ 500 µm	2 400 cm ²

Uncured Properties

Viscosity @ 25 °C	29 000 cP
Density	1.0 g/mL
Solids Content	50 %

Application Instructions

Read the product SDS and Application Guide for more detailed instructions before using this product (downloadable at www.mgchemicals.com).

Recommended Preparation

Clean the substrate with Isopropyl Alcohol, MG #824, so the surface is free of oils, dust, and other residues.

1. Apply 500 to 760 μm to the desired area.
2. For better coverage control, use a stencil.
3. If product is too thick, thin it with deionized (D.I.) water.
- 4 Do not remove mask until product becomes completely translucent.

Cure Instructions

Allow to cure at room temperature for 1 hour, or cure in an oven at one of these time/temperature options:

- 30 min @ 65 °C
- 20 min @ 80 °C

Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight. To maximize shelf life, recap product firmly when not in use.

Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

